



DESCRIPTION:

The products are 6-pin thyristor opto-couplers. The device combines an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon random-phase photo triac in a plastic DIP6 package with different lead forming options. With the robust coplanar double mold structure, the device provides the most stable isolation feature. The products are widely used in solenoid/valve controls, lighting controls, motor controls, temperature controls, static AC power switches, solid state relays, interfacing microprocessors up to 265 V_{AC} peripherals.

MAIN FEATURES

High isolation 5000 VRMS

DC input with random-phase photo triac output

Operating temperature range -55 to 110

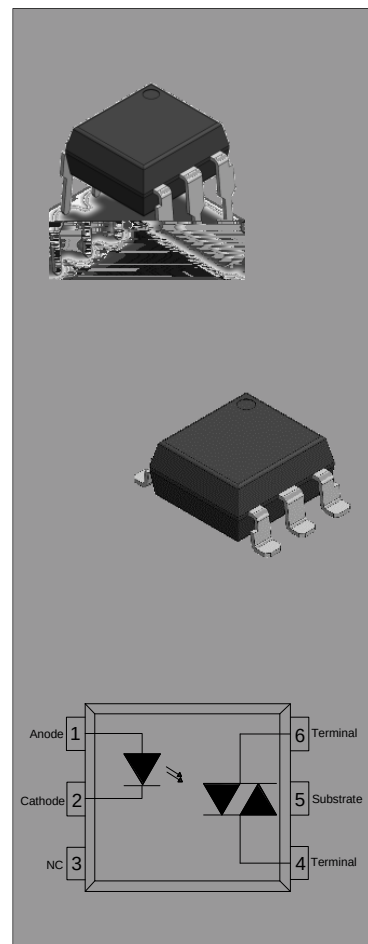
REACH & RoHS compliance

HBM: H3A; MM: M4; CDM: C3

CQC approved

VDE approved

UL approved



ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

Input	Forward Current	I _F		50	mA
	Peak Forward Current	I _{FP}		1 ^①	A
	Reverse Voltage	V _R		6	V
	Power Dissipation	P _D		75	mW
Output	Off-state Output Terminal Voltage	V _{OFF}	JOCSR22X	600	V
			JOCSR32X	800	
	Peak On-state Current (100μs pulse, 120 pps)	I _{TP}		2.5	A
	On-state RMS Current	I _{T(RMS)}		150	mA
	Peak Repetitive Surge Current (P _W =10 ms)	I _{TSM}		1.5	A
	Output Power Dissipation	P _O		250	mW



Total Power Dissipation	P_{tot}	325	mW
Isolation Voltage	V_{iso}	5000 ^②	V _{rms}
Operating Temperature	T_{opr}	-55~110	°C
Junction Temperature	T_j	125	°C
Storage Temperature	T_{stg}	-55~125	°C
Soldering Temperature	T_{sol}	260	°C
Peak pulse voltage ($T_j=25^{\circ}\text{C}$; non-repetitive, off-state)	V_{pp}	1	kV

NOTE1: μ

NOTE2:

ELECTRICAL CHARACTERISTICS (Temperature=25°C)

Input	Forward Voltage	V_F	$I_F=10\text{mA}$	-	1.2	1.5	V
	Reverse Current	I_R					

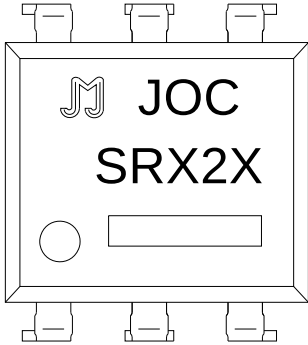
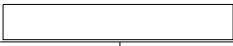


ORDERING INFORMATION

J	OC	S	R	2	2	A	-D6P/S	/
JieJie Microelectronics Co., Ltd.	Opto Coupler	SCR	Random phase			A: $I_{FT} \leq 10mA$ B: $I_{FT} \leq 5mA$ C: $I_{FT} \leq 3mA$ $I_{T(RMS)}: 150mA$	P:DIP6 S:SMD6	S:T3 L:T4
					2: $V_{OFF} \geq 600V$ 3: $V_{OFF} \geq 800V$			

Packing Quantity			
Option	Quantity	Quantity – Inner box	Quantity –Outer box

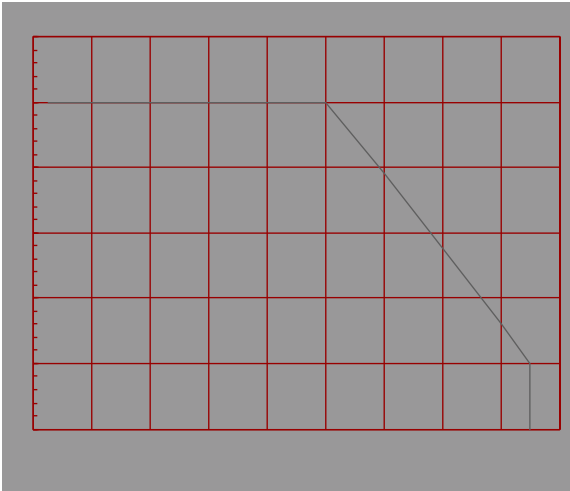
MARKING

	 Production Information Code
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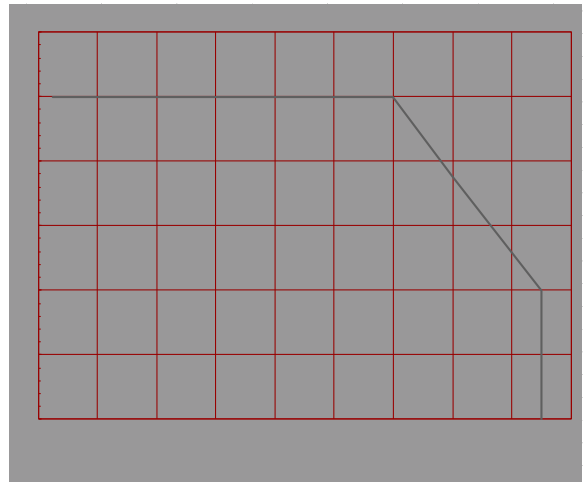


Characteristics Curves

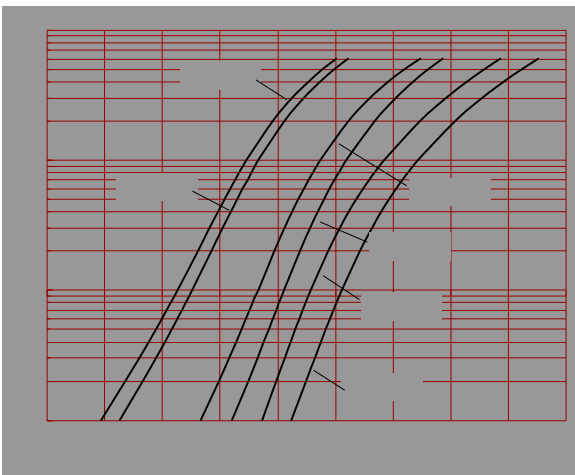
Max. Allowable LED Forward Current vs. Ambient Temperature



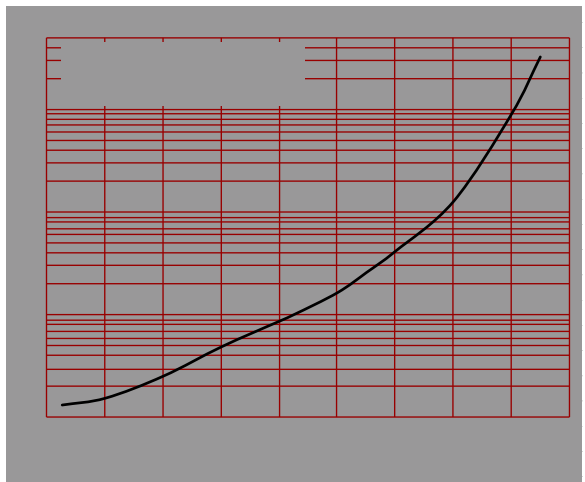
On-state Terminal Current vs. Ambient Temperature



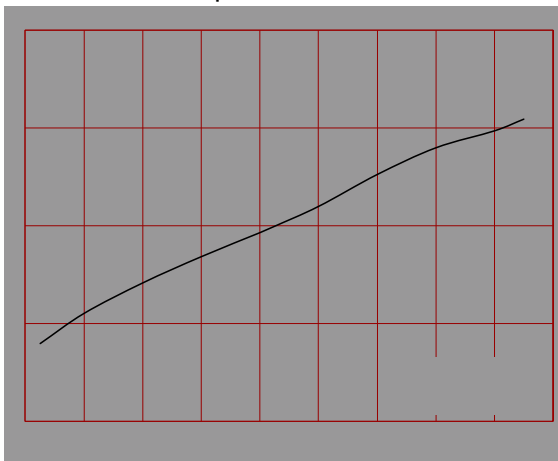
Forward Current vs. Forward Voltage



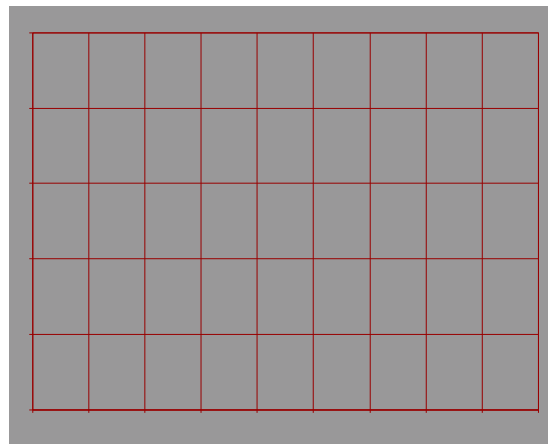
Normalized Off-state Terminal Current vs. Ambient Temperature



Normalized Off-state Terminal Voltage vs. Ambient Temperature

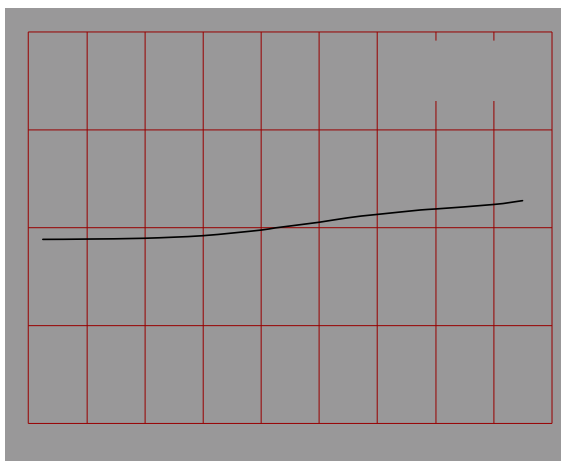


Normalized Trigger Current vs. Ambient Temperature

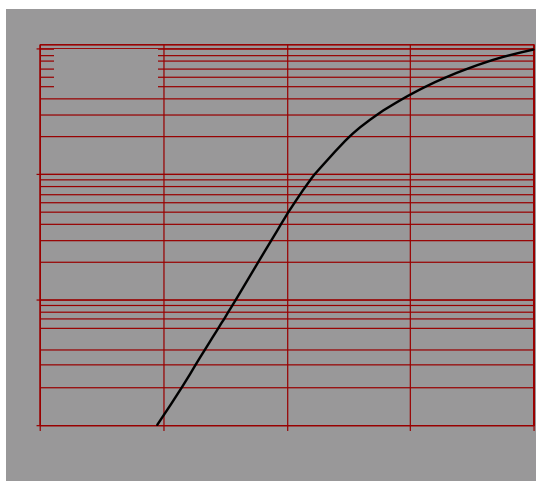




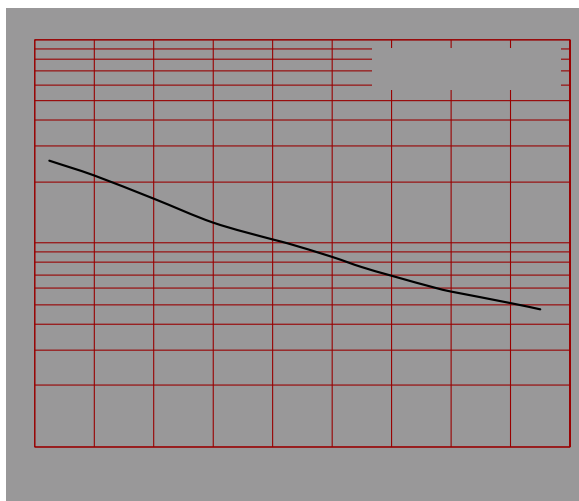
Normalized On-state Terminal Voltage vs. Ambient Temperature



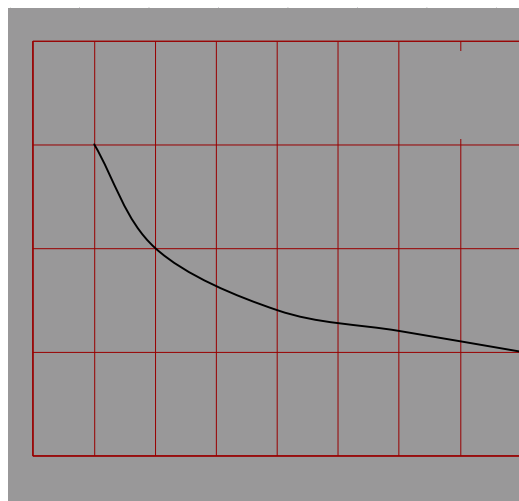
On-state Terminal Voltage vs. On-state Terminal Current



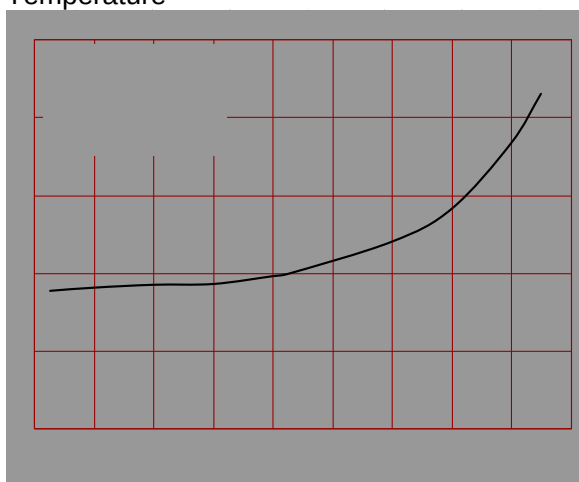
Normalized Holding Current vs. Ambient Temperature



Turn On Time vs. Forward Current



Normalized Turn On Time vs. Ambient Temperature





TEST CIRCUITS

Test Circuits of Turn On Time

Waveforms of Turn On Time



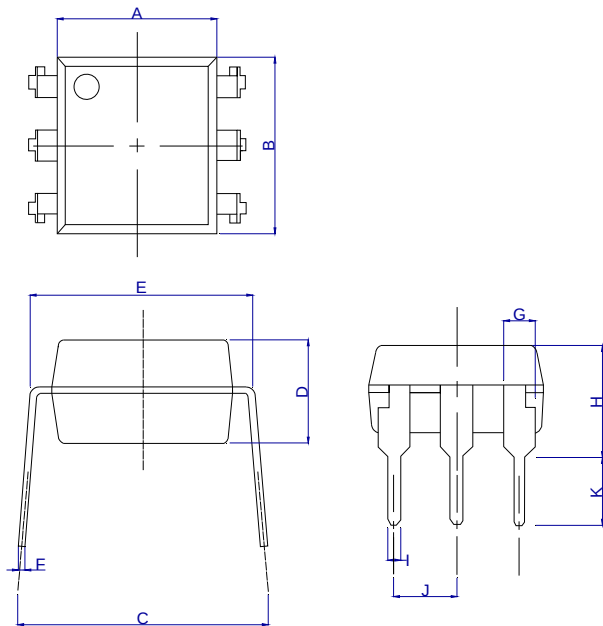


Test circuit for inductive and resistive loads to IEC-61000-4-5 standards

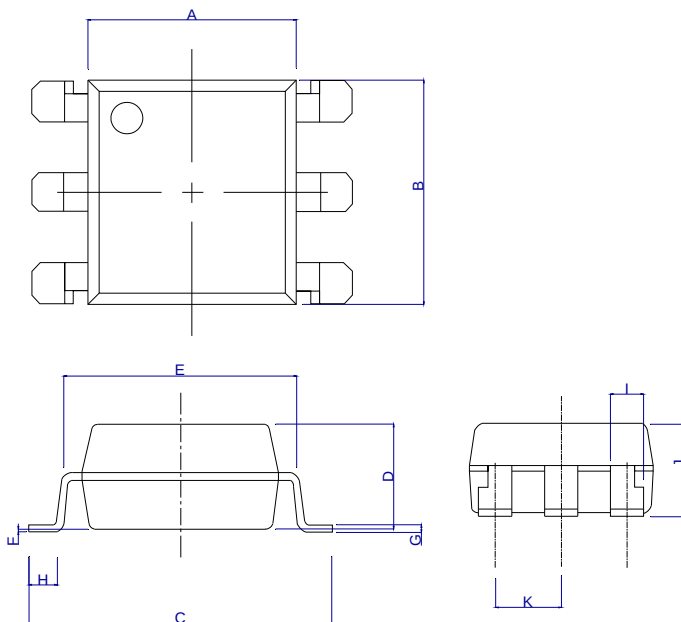




Package Dimension (Unit: mm)



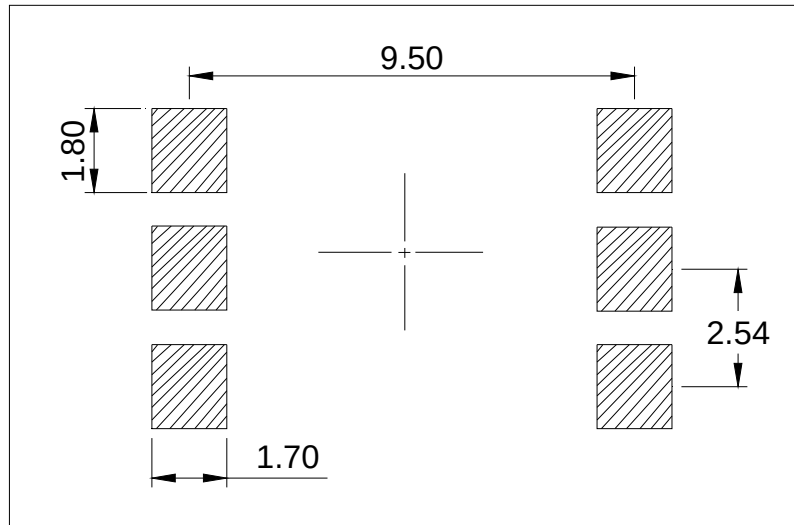
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	6.92		7.32	0.272		0.288
C	7.15		8.95	0.281		0.352
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.15		0.35	0.006		0.014
G	1.15		1.35	0.045		0.053
H	3.90		4.50	0.154		0.177
I	0.40		0.60	0.016		0.024
J	2.29		2.79	0.090		0.110
K	2.24		3.24	0.088		0.128



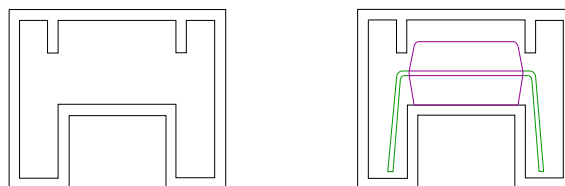
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	6.92		7.32	0.272		0.288
C	9.50		10.50	0.375		0.413
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.05		0.35	0.002		0.014
G	0.16		0.36	0.006		0.014
H	0.60		1.40	0.024		0.055
I	0.90		1.50	0.035		0.059
J	3.30		3.90	0.130		0.154
K	2.29		2.79	0.090		0.110



RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

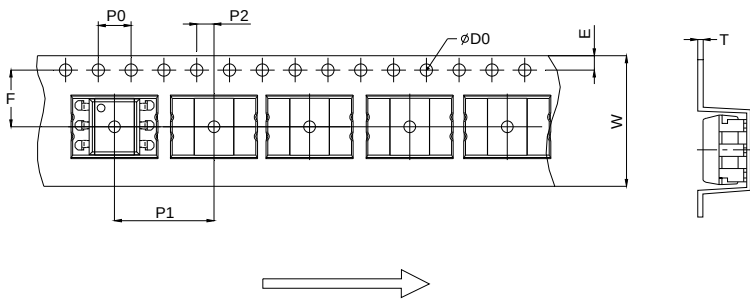


TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

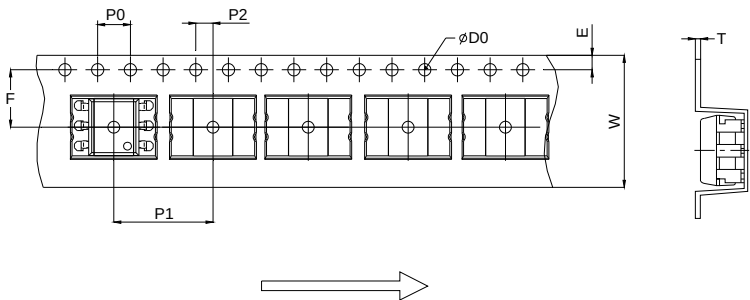




CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)



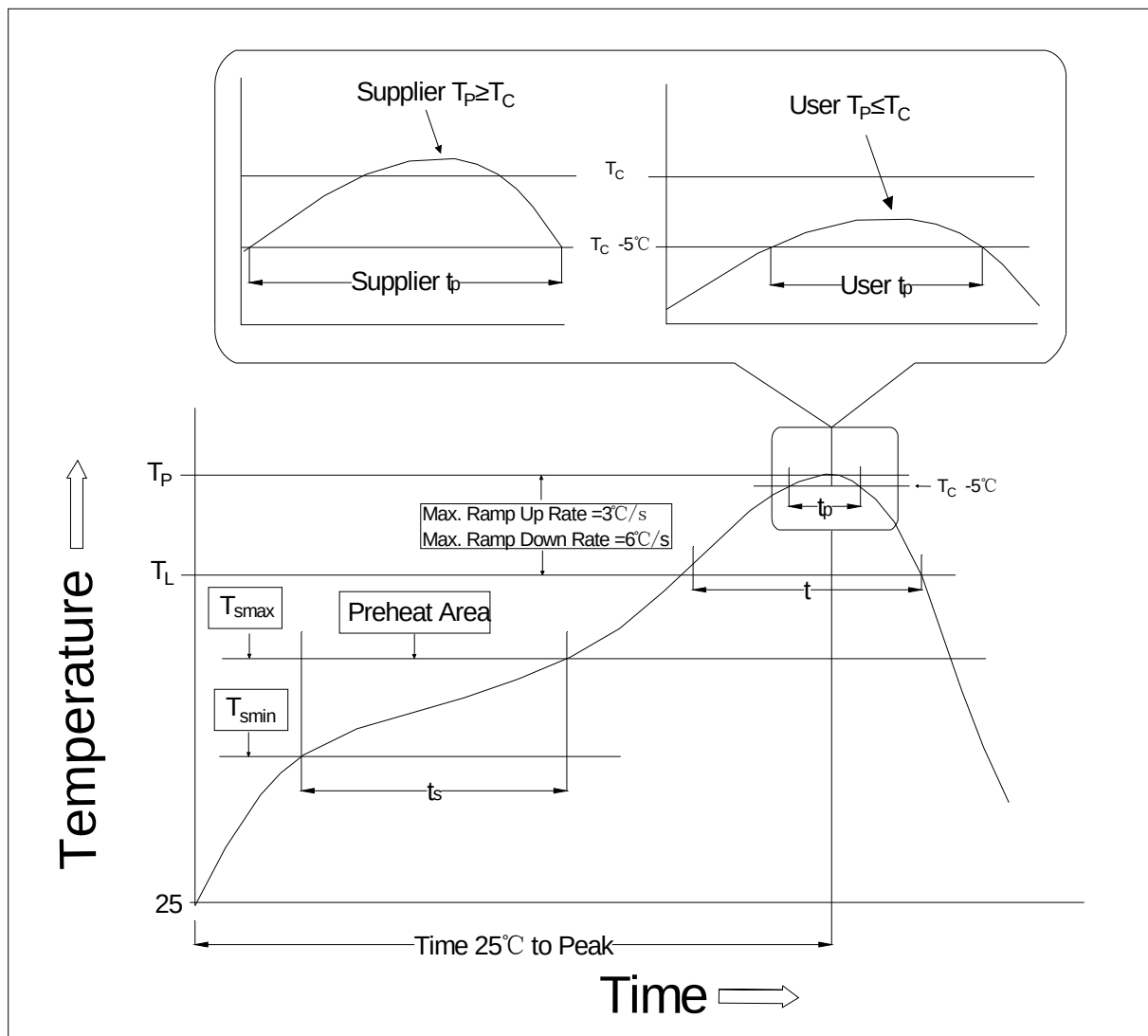
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.70	16.00	16.30	0.618	0.630	0.642



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.70	16.00	16.30	0.618	0.630	0.642



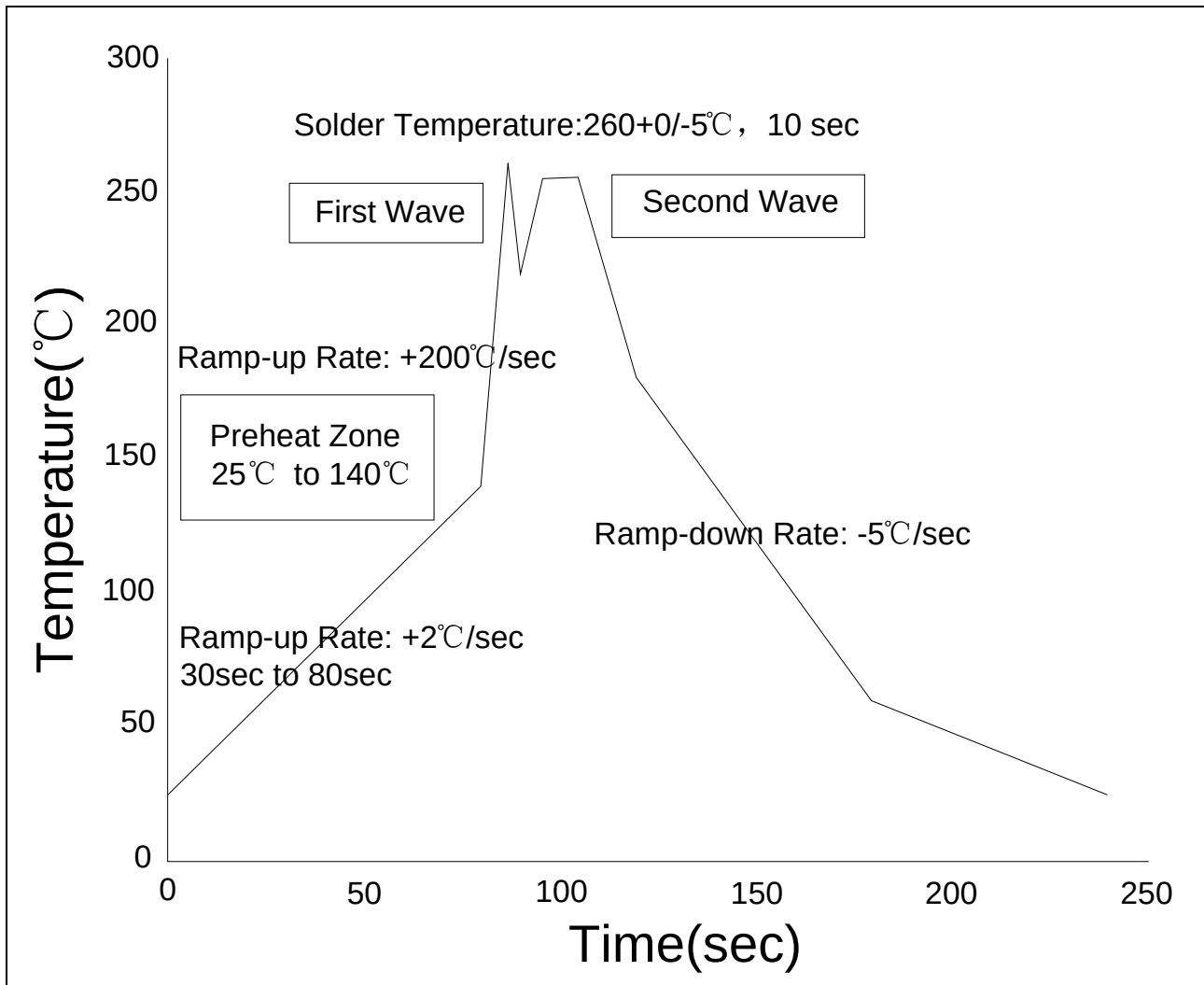
REFLOW INFORMATION



Temperature Min. (T _{smin})	100°C	150°C
Temperature Max. (T _{smax})	150°C	200°C
Time (t _s) from (T _{smin} to T _{smax})	60-120 seconds	60-120 seconds
Ramp-up Rate (t _L to t _P)	3°C/second max.	3°C/second max.
Liquidus Temperature (T _L)	183°C	217°C



WAVE SOLDERING



HAND SOLDERING BY SOLDERING IRON

Soldering Temperature	360±5°C
Soldering Time	3s max.



Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;
Recommend storage humidity: <60%;
MSL level: MSL 1

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